

Title (en)
PRODUCTION LINE FOR SOLDERING

Title (de)
FERTIGUNGSLINIE ZUM LÖTEN

Title (fr)
LIGNE DE FABRICATION POUR LE BRASAGE

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Application
EP 17724543 A 20170517

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Abstract (en)
[origin: WO2017207272A1] The invention relates to a production line for soldering components (1) onto a printed circuit board (2), comprising: a soldering furnace (3) with at least two temperature zones (Z1, Z2,...), in which there is a predetermined temperature profile (Tp), a transporting device (4), which is designed to transport the printed circuit boards (2) through the temperature zones (Z1; Z2,...) of the soldering furnace (3) in a transporting direction (Rt), and also a control device (5); wherein, in at least one temperature zone (Z1; Z2,...), at least two heating elements (60, 61,...) are designed and arranged in such a way that a surface (10) to be soldered of the printed circuit boards (2) transported through the soldering furnace (3) is heated by the heating elements (60, 61,...), wherein the heating elements (60, 61,...) are arranged offset one behind the other in the transporting direction (Rt) and are facing the surface (10) to be soldered, wherein, in at least one of the temperature zones (Z1; Z2,...), at least two fans (70, 71,...) are provided, arranged offset one behind the other in the transporting direction (Rt) and facing the surface (10) to be soldered, and wherein the control device (5) is designed for activating the heating elements (60, 61,...) and the fans (70, 71,...) in such a way that the predetermined temperature profile (Tp) is obtained on the surface (10) to be soldered of the printed circuit board (3) in the temperature zones (Z1; Z2,...).

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